

What is claimed is:

1. A one system module in which a socket is placed between a ceramic PCB and an epoxy PCB that are disposed inside a module body, a power element and signal elements are respectively mounted on the upper portion of each PCB, wherein a groove is made at the lower side surface and at the middle side surface of the module body to support the ceramic PCB and the epoxy PCB formed in two-story structure, and a power pin for receiving a power signal from an external source is mounted on the ceramic PCB and a signal pin for receiving various signals from an external source is mounted on the epoxy PCB

2. The one system module according to claim 1, wherein aluminum wire bonding is performed to mount elements on the ceramic PCB, while gold wire bonding is performed to mount a microcomputer on the epoxy PCB.

3. The one system module according to claim 1, wherein the power pin as a power board is mounted on the ceramic PCB by soldering, while the signal pin as a signal board is mounted on the epoxy PCB by soldering.

4. The one system module according to claim 1, wherein the power pin is mounted on the ceramic PCB while the signal pin is mounted on the epoxy PCB, thereby reducing the pins in number of the socket.